

Korea National NanoFab Center Recognizes EV Group with Supplier Excellence Award – February 9, 2022

semiconductor packaging news

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February 9, 2022

[What Causes Semiconductor Aging?](#)

Semiconductor technology has evolved to the point where no one can assume chips will last forever. If not carefully considered, aging can shorten the life of an IC below the needs for an intended application. Aging is well studied in technology circles, but while others less directly involved may understand at a general level this is a problem, it's not always obvious why. So what exactly ...

Semiconductor Engineering



[Prevent Costly Die Migration.](#)

Avoid the high costs associated with die migration from the pockets of chip trays with Gel-Pak's New LCS2™ Waffle Pack Lid. Learn more.

Gel-Pak, a Division of Delphon



[DIE Stacking on a Small Area](#)

Assembly process where chips are stacked on top of one another on a substrate. This vertical integration allows a compact arrangement of different circuits with different dimensions on a small area.

Tresky Automation



[VIEWPOINT 2022: Bob LePage, Marketing Manager, Circuit Technology Center](#)

Thanks to our dedicated team of highly skilled Repair and Rework professionals, 2021 was another year of solid growth for Circuit Technology Center, despite the challenges presented by the ongoing global pandemic. We are pleased to report that we have continued to invest in equipment, human capital, our facility ...

Circuit Technology Center



[Balancing Throughput and Process Control for RF Power Amplifier Assemblies](#)

Learn techniques for optimizing RF transistor packaging during the die bonding process. Learn how to maximize throughput in production while implementing ...

Technical Paper

[EU rolls out a red carpet for TSMC and other semiconductor giants](#)

The European Union announced a blueprint to make one-fifth of the world's microchips, saying it was "open for business" to semiconductor giants from Taiwan and other ...

South China Morning Post

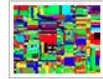
Technical Papers

- [Advanced Packaging and Electronic Assembly Cleaning Fluid Innovation](#)
- [Improving Si and SiC Wafer Dicing Yields with Thermal Laser Separation](#)
- [Critical Considerations for Electronic Component Tin Whisker Mitigation](#)
- [Why AgCoat@ Prime, why now?](#)
- [The New Technology Solutions for Advanced SiP Devices](#)
- [The Effects of Long-Term Storage on Solderability of Components](#)
- [Optimizing cycle times in the semiconductor industry with Openair-Plasma](#)

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See answer below.

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MRSI Systems



Press Releases

[Korea National NanoFab Center Recognizes EV Group with Supplier Excellence Award](#)

EV Group (EVG) announced that it has received a Supplier Excellence Award from the Korea National NanoFab Center (NNFC), a nano-technology R&D infrastructure for academia ...

EV Group

[Teledyne Relays Announces New Non-Latching, SPDT RF Relay](#)

Teledyne Relays announces new wide temperature range, hermetic relays operating up to 18 GHz. The new RF131 and GRF131 single-pole doublethrow (SPDT) models ...

Teledyne Relays

[Worldwide Silicon Wafer Shipments and Revenue Set New Records in 2021](#)

Worldwide silicon wafer area shipments in 2021 increased 14% while wafer revenue rose 13% compared to 2020, topping \$12 billion, to reach new all-time highs, the SEMI ...

SEMI

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3D Technology Development is a World-Wide Activity

The CHIPS Act, which is finally gaining some momentum in Congress, is looking at how to improve the United States' competitiveness as well as supply chain in the ...

3DInCites

Global chip shortage gives US manufacturing a boost

When you can't buy that Sony PS5 or Ford F-150 pickup, blame the chip shortage. A worldwide problem triggered by the COVID-19 pandemic has metastasized into a ...

CNET

Softbank's sale of Arm scrapped

Softbank Group Corp yesterday confirmed that the US\$40 billion sale of chip business Arm Ltd to Nvidia Corp had collapsed because of "significant regulatory challenges" ...

Taipei Times

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A.L.M.T. Corp.



What Year Was It?

Satchel Paige Nominated to Baseball Hall of Fame

Pitcher Leroy "Satchel" Paige becomes the first Negro League veteran to be nominated for the Baseball Hall of Fame.



The day was Feb 9. What year was it?

Q&A: Here's How AI Will Change Chip Design

The end of Moore's Law is looming. Engineers and designers can do only so much to miniaturize transistors and pack as many of them as possible into chips. So they're ...

IEEE Spectrum

Doomed from the start? Why Nvidia failed to buy Arm from SoftBank

Nvidia's bid to buy Arm from SoftBank has finally ended in failure. The semiconductor giants issued a joint statement Tuesday saying the deal has been scrapped due ...

CNBC

Infineon aims to ramp up in-house production in 2022

German-based automotive and power semiconductor supplier Infineon is planning to ramp up in-house production in 2022 as it expects semiconductor demand to continue ...

Digitimes

The XRF engineered for semiconductors

Polycapillary optics focus to 7.5µm FWHM. X-Y stage with >300mm travel and +/- 1µm stage precision. Z-protection prevents sample collision. Auto wafer handling workstations. [Read more.](#)
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Master Bond



Intel embraces RISC-V for foundry service business opportunities

Intel announced a new US\$1 billion fund on February 7 to build a foundry innovation ecosystem and will collaborate with several RISC-V standard IC design firms. ...
Digitimes



Chip Assembly & Solder Rework



Laplace Systems
www.pactech.de

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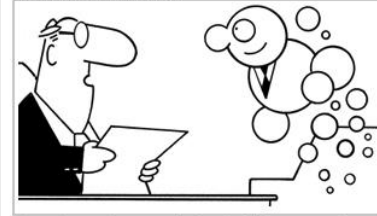


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Cartoon of the Day



"So what makes you think a bubbly personality would be an asset to this company?"
Copyright © Randy Glasbergen

Optimizing cycle times with Openair-Plasma

Plasma surface treatment has uses in semiconductor manufacturing, such as wire bonding, die bonding, thermal compress bonding, and pre-molding.
Plasmatreat GmbH



Calendar

- **Feb 9, 2022: SEMICON Korea 2022 Hybrid**
- **Feb 10, 2022: Overview of Semiconductor Manufacturing/Santa Clara, Ca**
- **Feb 15, 2022: Wafer-Level Packaging Symposium**
- **Feb 28, 2022: Wafer Fab Processing Webinar**

The XRF engineered for semiconductors

Polycapillary optics focus to 7.5µm FWHM. X-Y stage with >300mm travel and +/- 1µm stage precision. Z-protection prevents sample collision. Auto wafer handling workstations. Read more.
Bowman XRF



MRS™ Sensor for Challenging Measurement & Inspection

Use the NanoResolution MRS™ Sensor for 3D and 2D metrology and inspection in one pass.
Learn more.
CyberOptics Corporation



Test Your Knowledge Answer

How many times is the capacity of a pipe increased if the diameter is doubled?
Answer: Four

NEWSLETTER ARCHIVES